IPC  ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both Thi	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and M	ials and Mfg Information			
upplier Inforn															
Company name*			Company unique ID			ι	Unique ID Authority				Response Date*				
onsemi											2024-05-18				
Contact Name		Т	Title - Contact			F	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	ards	P	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
authorized Represe	entative*	Т	Title - Representative			F	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewa	ards	P	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
Requesto	Requester Item Number Mfr Ite		umber			Effective Date	Versio	on	Manufacturing Site		Weight*	UOM	Unit Type		
		NTMFS3D2	TMFS3D2N10MDT PTNG 100V Low Q3 SO8FL		Q3.2mOhm N-FE	Т, НЕ	2024-05-18		MY1			131.06	mg	Each	
<b>Ianufacturing</b>	Proccess Informatio	n													
Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 MSI		-STD-020 MSL Ra	ating	Peak Process Body Temperature Max Time at Pea		Temperat	ure Numb	er of Reflow Cyc	eles			
Matte Tin (Sn) - annealed			CU Alloy 1		1		260	C 30		secon	ds 3				
omments															
vel 1 - maximum t	ime at peak temperature	during solde	ring is 10-30	0 seconds											
or more informati	on regarding material co	mposition ple	ease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this f											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	15.59	mg	Supplier	Iron (Fe)	7439-89-6		0.0156	mg
			Supplier	Copper (Cu)	7440-50-8		15.5697	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0047	mg
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach Solder	4.98	mg	Supplier	Silver (Ag)	7440-22-4		0.1245	mg
			A	Lead (Pb)	7439-92-1	7a	4.6065	mg
			Supplier	Tin (Sn)	7440-31-5		0.249	mg
Lead Frame	58.99	mg	Supplier	Silver (Ag)	7440-22-4		0.0354	mg
			Supplier	Iron (Fe)	7439-89-6		0.059	mg
			Supplier	Copper (Cu)	7440-50-8		58.8779	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0177	mg
Mold Compound-Black	46.2	mg		Epoxy resin	proprietary data		3.465	mg
			Supplier	Phenolic Resin	Proprietary Data		1.155	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.465	mg
			Supplier	Carbon Black (C)	1333-86-4		0.231	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		37.884	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg